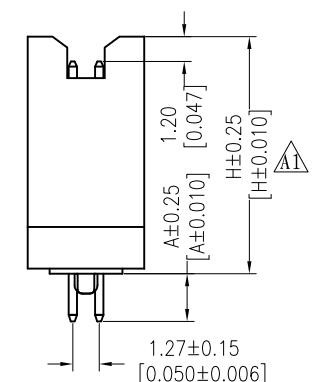
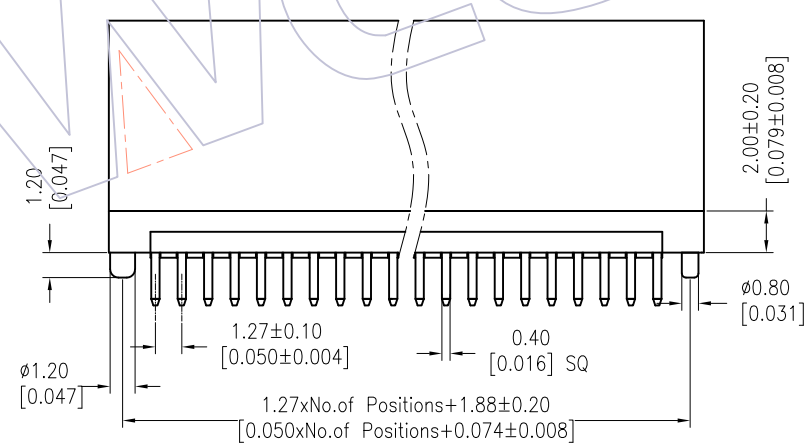
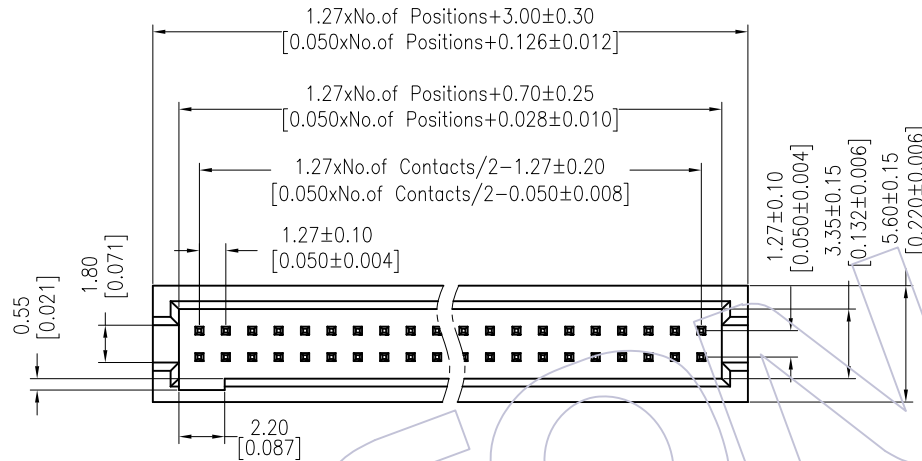
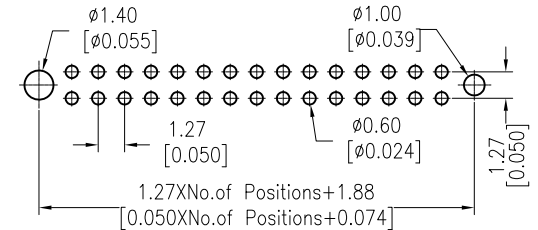


# HSF

NOTES:  
 Current Rating:1.0AMP  
 Contact Resistance:20mΩ max  
 Withstand Voltage:500V AC/DC  
 Insulation Resistance:1000MΩ min  
 Operation Temperature:-40°C to +105°C

Contact Material:Brass  
 Contact plating:Au or Sn Over Ni  
 Insulator Material:LCP+30%GF(UL94V-0)  $\Delta\Delta$

Recommended P.C.B Layout (Top Side)  
 (PCB BOARD TOLERANCE  $\pm 0.05$ )



## Ordering Information

### 3100-XX S XX B XXX X 1

No. of Pins	Contact Plating	Total High	Packing
10 34	G0=Gold Flash	086=8.6mm	T=Tube
14 40	G1=3u"Gold	092=9.2mm	P=Tube+CAP
16 44	G2=5u"Gold	096=9.6mm	
20 50	G3=10u"Gold	098=9.8mm	
24 60	G4=15u"Gold	106=10.6mm	
26 64	G5=30u"Gold	109=10.9mm	
30 80	S0=Gold Flash/Tin	112=11.2mm	
32 100	S1=3u"Gold/Tin	114=11.4mm	
	S2=5u"Gold/Tin	117=11.7mm	
	S3=10u"Gold/Tin	124=12.4mm	
	S4=15u"Gold/Tin	143=14.3mm	
	S5=30u"Gold/Tin	154=15.4mm	
	SN=Tin	158=15.8mm	
		175=17.5mm	
		188=18.8mm	

Item	Dip Length	Mating
Standard	2.30	2344
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A3	2015/04/17	Modify	$\Delta 3$	OPERATION	DRAW	2015/04/17	UNIT	mm	3100-XXSXXBXXXX1
A2	2014/12/25	Modify	$\Delta 2$	X.X ±0.40	Allen		inch		
A1	2014/07/18	Modify	$\Delta 1$	X.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE:
A0	2013/01/15	NEW		X.XXX ±0.15	APPROVE	DATE	SHEET	1/1	1.27 BOX HEADER
				Angle ± 3'			PROJ.	$\phi$	180° DIP WITH POST
				DIM TOL					Customer NO.